

AMENDMENTS TO THE CLAIMS:

Kindly amend claim 1, as shown below.

This listing of claims will replace all prior versions and listings of claims in the Application:

Claim 1 (currently amended): A stacked semiconductor storage device comprising, in combination, a lower chip and an upper chip superimposed on a substrate, said semiconductor storage device further comprising:

a wiring substrate having wiring patterns thereon, interposed between and in direct contact with both said lower chip and said upper chip, for relaying electric connection between bonding pads on said upper chip and bonding pads on said substrate, wherein the bonding pads on said upper chip are arranged in a line running perpendicular to a line of bonding pads on the substrate;

wherein said upper chip has an upper and a lower surface, said lower surface facing said substrate; and

wherein the bonding pads on said upper chip that connect to the bonding pads of said substrate are disposed on the lower surface of said upper chip.

Claim 2 (previously amended): A stacked semiconductor storage device as claimed in claim 1, wherein there are provided a first terminal connected to a terminal on a surface of said upper chip, a second terminal connected to a terminal on a surface of said substrate, and a wiring pattern for connecting said first and said second terminals on the surface of said wiring substrate.

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Claim 3 (previously amended): A stacked semiconductor storage device as claimed in claim 2, further comprising:

 a first bonding wire for connecting said terminal of the surface of said upper chip with said first terminal; and

 a second bonding wire for connecting said terminal of the surface of said substrate with said second terminal.

Claim 4 (previously amended): A stacked semiconductor storage device as claimed in claim 1, wherein there is provided a wiring pattern whose one end is connected to a terminal on a rear surface of said upper chip, and whose other terminal is connected to a terminal on a surface of said lower chip.

Claim 5 (previously amended): A stacked semiconductor storage device as claimed in claim 2, wherein said terminal of the surface of said lower chip is connected to said terminal of the surface of said substrate by a third bonding wire.

Claim 6 (previously amended): A stacked semiconductor storage device as claimed in claim 4, wherein said terminal of the surface of said lower chip is connected to said terminal of the surface of said substrate by a third bonding wire.

Claim 7 (previously amended): A stacked semiconductor storage device as claimed in claim 1, wherein said wiring substrate is a sheet wiring substrate.

Claim 8 (previously amended): A stacked semiconductor storage device as claimed in claim 1, wherein said wiring substrate is a board wiring substrate.

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